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PTO/SB/21 (12-97)

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TRANSMITTAL FORM (to be used for all correspondence after initial filing) BOX: NON-FEE AMENDMENT Express Mail Receipt No.	Application / Conf. No.	09/879,875 / 4969
	Filing Date	June 11, 2001
	First Named Inventor	Abu K. Eghan
	Examiner Name	V. Bhagawan
	Group Art Unit	2829
	Issue Fee Batch No.	
	Attorney Docket Number	X-901 US

ENCLOSURES (check all that apply)		
<input type="checkbox"/> Fee Transmittal Form	<input type="checkbox"/> Assignment Papers (with Recordation Cover Sheet)	<input type="checkbox"/> After Allowance Communication to
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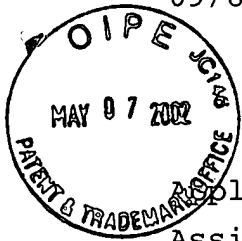
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X-901 US
09/879,875

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PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Abu K. Eghan et al.
Assignee: Xilinx, Inc.
Title: High Performance Flipchip Package That
Incorporates Heat Removal With Minimal Thermal
Mismatch
Serial No.: 09/879,875 File Date: 6/11/2002
Examiner: Venkatesha Bhagawan Art Unit: 2829
Docket No.: X-901 US

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AMENDMENT IN RESPONSE TO FIRST OFFICE ACTION

Dear Sir:

In response to the First Office Action mailed from the Patent Office on January 30, 2002, please replace the abstract and the following claims as indicated.

IN THE ABSTRACT

Please replace the Abstract with the following:

A semiconductor flipchip package includes a central cavity area on the first major side for receiving a flipchip die therein. The package substrate is substantially made from a single material that serves as the support and stiffener and provides within the cavity floor all the connecting points for flipchip interconnection to the silicon die. The integral cavity wall serves as a stiffener member of the package and provides the required mechanical stability of the whole arrangement without the need for a separate stiffener material to be adhesively attached. The cavity walls may contain extra routing metallization to create bypass capacitors to enhance electrical